



Flip Chip Substrates BT to ABF Conversion for Selected Aerospace & Defense 'XQ' Virtex-4 FPGA Devices

XCN09031 (v1.0) October 26, 2009

Product Change Notice

Overview

The purpose of this notification is to announce conversion of substrate material changed from BT to ABF build-up for selected Aerospace & Defense 'XQ' Virtex[®]-4 FPGA device/package. There is no change to the form, fit, function or reliability with this change.

Description

For the below affected products, substrate materials will be converted from BT to ABF build-up. The reason for the change is the phase out of UV laser equipment support at substrate supplier. To ensure continuity of supply for flip chip products, BT will be replaced by ABF since UV laser is not required to form vias with ABF material. The ABF materials set is already qualified and in production for other Virtex[®]-II Pro FPGA, Virtex-4 FPGA and Virtex[®]-5 FPGA products.

Products Affected

This change affects all speed, package, and temperature variations of the Aerospace & Defense 'XQ' devices. Affected part numbers are included in the following table(s):

Table 1: Product Changes

Xilinx Product	Package	Change Description
XQ4VLX40	FF(G)668	Build-up materials set change from BT to ABF
XQ4VLX100	FF(G)1148	Build-up materials set change from BT to ABF

Key Dates and Ordering Information

Xilinx will begin to ship production using ABF substrate materials on or after 25th January 2010 (90 days of PCN date).

Qualification Data

Qualification data & device reliability report for Virtex-4 FPGA devices is available in the [UG116](#). The extended qualification data related to this PCN is available in the [RPT141](#).

Response

No response is required. For additional information or questions, please contact [Xilinx Technical Support](#).

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Additional Documentation

Qualification Report (RPT141)

<https://secure.xilinx.com/webreg/clickthrough.do?cid=140202>

Device Reliability Report (UG116):

http://www.xilinx.com/support/documentation/user_guides/ug116.pdf

Revision History

The following table shows the revision history for this document.

Date	Version	Revision
10/26/09	1.0	Initial release.

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